



FUKUCOM COMPANY LTD.

福 靈 有 限 公 司

FLAT P, 3/F., EVEREST INDUSTRIAL CENTRE, 396 KWUN TONG ROAD,
KWUN TONG, KOWLOON, HONG KONG.

TEL: 852-2790 0314 FAX: 852-2790 0206

US1A THRU US1M

SURFACE MOUNT ULTRAFAST RECOVERY RECTIFIERS

Reverse Voltage – 50 to 1000 Volts

Forward Current – 1.0 Ampere

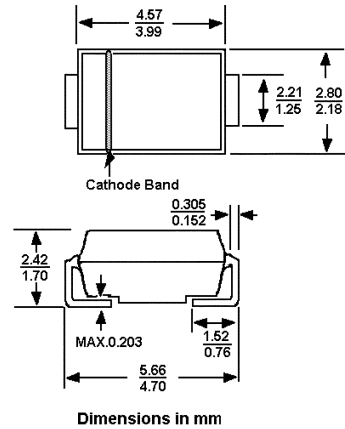
Features

- For surface mount applications
- Low profile package
- Built-in strain relief
- Easy pick and place
- Ultrafast recovery times for high efficiency
- Plastic package has Underwriters Laboratories Flammability Classification 94V-0
- High temperature soldering guaranteed: 260°C/10 seconds on terminals

Mechanical Data

- **Case:** JEDEC DO-214AC(SMA) molded plastic
- **Terminals:** Solder plated, solderable per MIL-STD-750, method 2026 guaranteed
- **Polarity:** Color band denotes cathode end

SMA DO-214AC

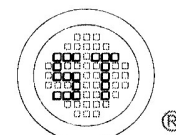


Maximum Ratings and Electrical Characteristics

Ratings at 25°C ambient temperature unless otherwise specified. Single phase, half wave, 60Hz, resistive or inductive load. For capacitive load, derate current by 20%.

	Symbols	US1A	US1B	US1D	US1G	US1J	US1K	US1M	Units
Maximum repetitive peak reverse voltage	V_{RRM}	50	100	200	400	600	800	1000	V
Maximum RMS voltage	V_{RMS}	35	70	140	280	420	560	700	V
Maximum DC blocking voltage	V_{DC}	50	100	200	400	600	800	1000	V
Maximum average forward rectified current at $T_L = 100^\circ\text{C}$	$I_{F(AV)}$	1.0							A
Peak forward surge current 8.3ms single half sine-wave superimposed on rated load (JEDEC Method)	I_{FSM}	30							A
Maximum forward voltage at 1A	V_F	1		1.3		1.7			V
Maximum DC reverse current $T_A = 25^\circ\text{C}$ at rated DC blocking voltage $T_A = 100^\circ\text{C}$	I_R	5 100							μA
Typical junction capacitance at 4V, 1MHz	C_J	17							pF
Typical thermal resistance ⁽¹⁾	$R_{\theta JL}$	30							$^\circ\text{C/W}$
Maximum reverse recovery time at $I_F = 0.5\text{A}$, $I_R = 1\text{A}$, $I_{rr} = 0.25\text{A}$	t_{rr}	50				75			ns
Operating and storage temperature range	T_J, T_S	-55 to +150							$^\circ\text{C}$

Note: (1) Thermal resistance from junction to lead mounted on P.C.B. with 0.3x0.3" (8.0x8.0 mm) copper pad areas.



SEMTECH

Dated : 28/04/2005



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RATING AND CHARACTERISTIC CURVES

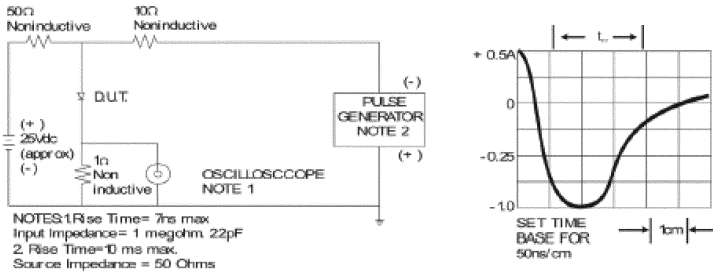


Fig. 1-REVERSE RECOVERY TIME CHARACTERISTIC AND TEST CIRCUIT DIAGRAM

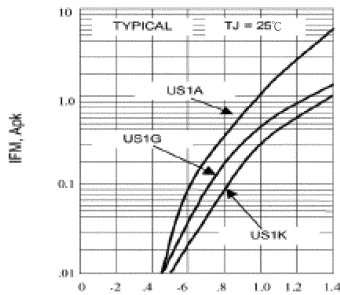


Fig. 2-FORWARD CHARACTERISTICS

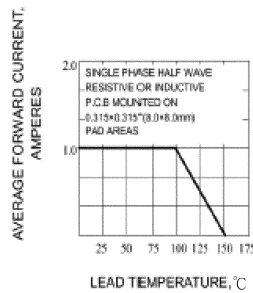


Fig. 3-FORWARD CURRENT DERATING CURVE

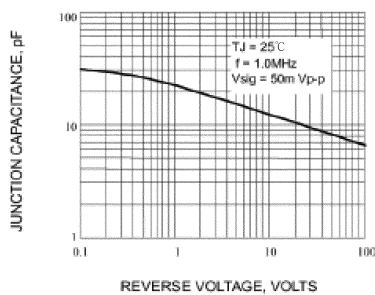


Fig. 4-TYPICAL JUNCTION CAPACITANCE

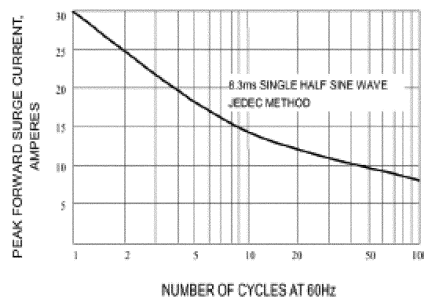
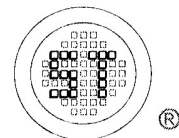


Fig. 5-PEAK FORWARD SURGE CURRENT



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